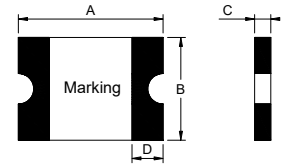


1、Physical Dimensions(size of 0402)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KASML010	0.95	1.25	0.45	0.75	0.35	0.65	0.10	White



2、Electrical Characteristics

- $V_{max} = 6\text{ Vdc}$
- $I_{max} = 40\text{ A}$

Model	Hold current and Trip current (AMPS)				Time To Trip (Sec.)		$P_{d\text{ typ}}$ (W)	R_{min} (Ω)	$R_{1\text{ max}}$ (Ω)
KASML010	25°C		70°C		0.5A @ 25°C		25°C, 6 V	25°C	25°C
	I-hold	I-trip	I-hold	I-trip	Min	Max	Max	0.150	2.000
	0.10	0.30	0.06	0.18	-	1.00	0.50		

I-hold: Holding Current: maximum current at which the device will not trip in 25°C or 60°C still air.

I-trip: Tripping Current minimum current at which the device will trip in 25°C or 60°C still air.

V_{max} : Maximum voltage device can withstand without damage at rated current.

I_{max} : Maximum fault current device can withstand without damage at rated voltage.

Time To Trip: Maximum time to trip(s) at assigned current.

$P_{d\text{ typ}}$: Rated working power.

R_{min} : Minimum resistance of device prior to trip at 25°C.

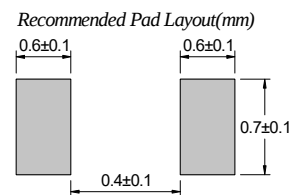
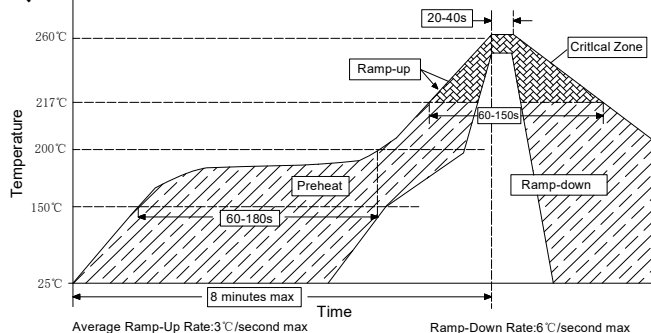
$R_{1\text{ max}}$: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

KASML010	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	0.13	0.12	0.11	0.10	0.09	0.08	0.07	0.06	0.05
Trip Current(A)	0.39	0.36	0.33	0.30	0.27	0.24	0.21	0.18	0.15

4、Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、Package Information

Packing quantity: 10000 pcs/Reel

Note: Reel packaging per EIA-481-1 standard